

IN THE CLAIMS:

1. (Previously Presented) A heat dissipating structure of a printed circuit board on which a circuit pattern is provided so that a heat generating part can be mounted, and which has a through hole formed at a site where the heat generating part is mounted from a surface on which the heat generating part is mounted to an opposite surface, wherein a heat dissipating member made of a material with a thermal conductivity higher than a board of the printed circuit board, and having a shape worked so that the heat dissipating member can be inserted into the through hole is mounted in the through hole with an adhesive interposed therebetween.
2. (Original) The heat dissipating structure of the printed circuit board of Claim 1, wherein a heat transfer plate made of a material with a thermal conductivity higher than the printed circuit board is adhered on the heat dissipating member of the printed circuit board and heat generated by a heat generating part mounted on the heat transfer plate is dissipated to the heat dissipating member by way of the heat transfer plate.

Claim 3-6 (Canceled)